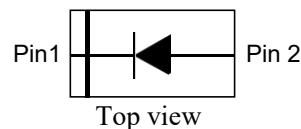


Feature

- Small mold type. (DFN1608-2L)
- Low I_R
- High reliability.



Applications

- Low current rectification

Construction

- Silicon epitaxial planar

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260°C
- Device meets MSL 1 requirements
- Pure tin plating: 7 ~ 17 um
- Pin flatness: ≤3mil

Electrical characteristics per line@25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	-	0.57	0.63	V	$I_F=1A$
Forward voltage	V_F	-	0.45	0.50	V	$I_F=0.5A$
Reverse current	I_R	-	-	0.1	mA	$V_R=40V$
Junction Capacitance	C_j	-	90	-	pF	$V_R=0V$ $f=1MHz$

Absolute maximum rating@25°C

Parameter	Symbol	limits	Unit
Reverse voltage (DC)	V_{RM}	40	V
Average rectified forward current	I_o	1	A
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	7	A
Operating Junction temperature Range	T_j	-55 to +125	°C
Storage temperature	T_{stg}	-40 to +125	°C

Typical Characteristics

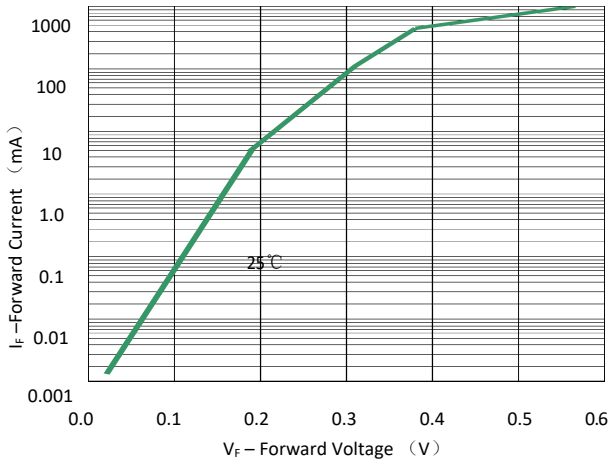


Fig 1. Forward Voltage

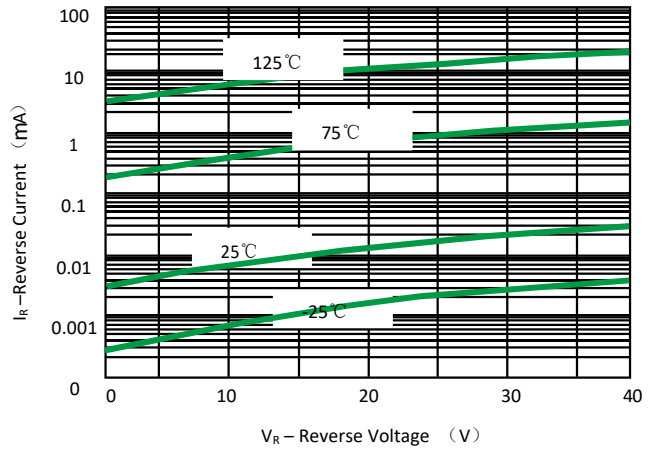
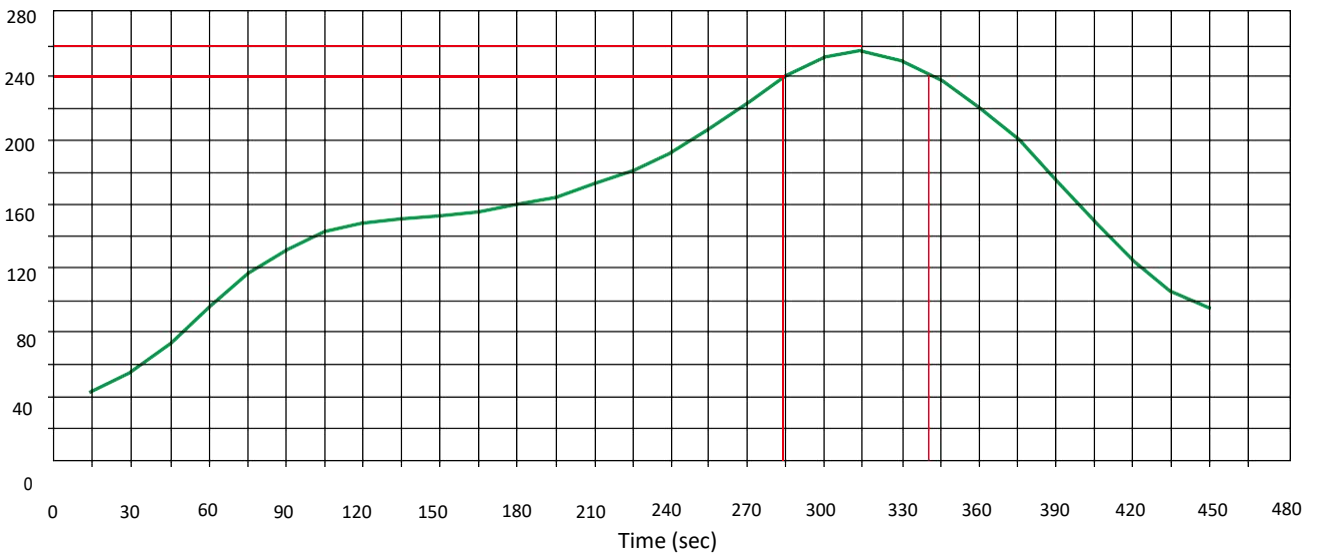


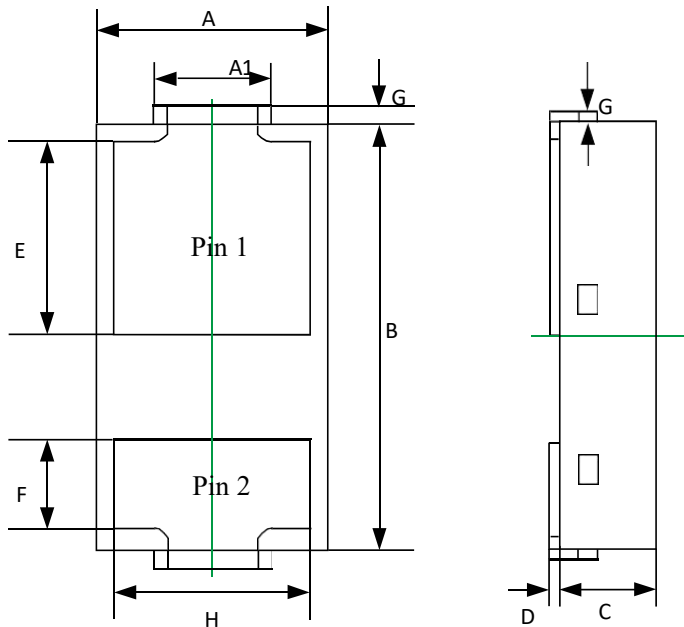
Fig 2. Leakage Current

Solder Reflow Recommendation

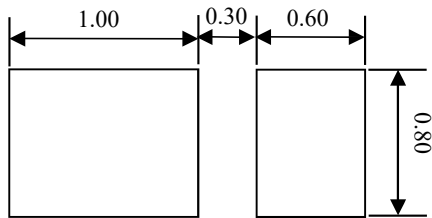
Peak Temp=257°C, Ramp Rate=0.802deg. °C/sec



Product dimension (DFN1608-2L)

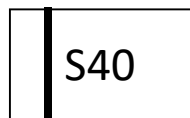


Dim	Millimeters	
	MIN	MAX
A	0.75	0.85
A1	0.00	0.25
B	1.55	1.65
C	0.46	0.55
D	0.00	0.04
E	0.72	0.80
F	0.32	0.40
G	0.00	0.10
H	0.67	0.75



Notes: This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

Marking information



Ordering information

Device	Package	Reel	Shipping
DS161-40THD02	DFN1608-2L(Pb-free)	7"	5000 / Tape & Reel